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ABSTRACT

FILM, AND METHOD FOR MANUFACTURING SEMICONDUCTOR PACKAGE

A film including a substrate, a base layer, and an adhesive layer in this order, in which the base layer includes a reaction cured product of a (meth)acrylic polymer and a curing agent, and the base layer has an elongation rate of 90% or more as measured by a tensile test at 25°C and a speed of 100 mm/min and determined by the following formula, 5 Elongation rate (%) = (elongation (mm) at break) × 100/(distance (mm) between grippers before applying tension).

Figure 1